

# Synchronization of GC5016 DDC/DUC on TSW4100 EVM

Vaibhav Shinde

#### ABSTRACT

TSW4100 is a digital repeater board containing two GC5016 chips which act as DDC and DUC. A repeater application requires syncronization between the DDC output and the DUC input data to observe the desired repeater functionality. This requires the DDC to operate as a master and DUC as the slave. However, the GC5016 is designed for Master mode only. The board uses FPGA to achieve this sychronization. However, there is a time when the FPGA logic and the synchronization method designed with the FPGA fails in practice. A method to achieve synchronization for lower decimation rates has been proposed in this application report which overcomes the glitch in the FPGA logic.

#### Contents

Theory behind Synchronization of Data	
Syncronization at Lower Decimation Rates	.4
Synchronization Test	.5

#### **Figures**

Figure 1.	DDC output and DUC input time alignment	.2
	Split IQ Mode	
•	Output of the Spli IQ Mode	
	Output of four channel Mode	

## Theory behind Synchronization of Data

There are two GC5016 chips on the TSW4100 board. One of them functions as the DDC, and the other functions as the DUC. Data to be repeated is fed to the input of the DDC. The DDC processes the data to the baseband and makes it available to the DUC. The DUC upconverts the data and sends it to the output section of the TSW4100 board. Ideally, the DDC should signal the DUC when data is available at its output. (DDC should act as a master to the DUC slave). However, the GC5016 which is used here as DDC, and the DUC can only functions as a master.



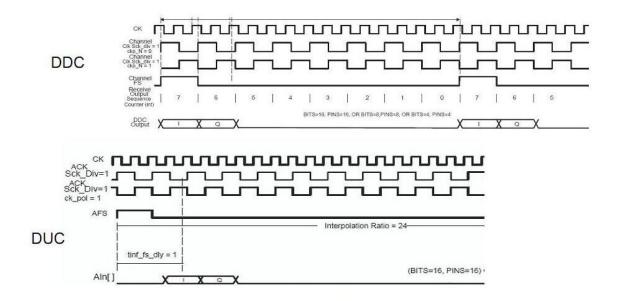


Figure 1. DDC output and DUC input time alignment

Figure 1 shows three clocks viz. CK, ACK and AFS. The clock CK is the primary clock used in GC5016. The ideas behind using a slower channel clock ACK is that it can be used as a reference for the relatively slower operating devices like the data convertors that reside in the singal chain. The data signal A0 and the frame strobe AFS are synchronized to the channel clock ACK. AFS indicates when the data is ready (DDC output) or expected to be ready (DUC input). Since GC5016 can only act as a master (as mentioned previously), the two frame strobes (DDC AFS and DUC AFS) need to be synchronized in order to synchronize the data. The only way to synchronize the data is by delaying the data at the output of the DDC so that it is present at the input of the DUC when it asserts a DUC AFS (i.e when the DUC expects the data at its input).

The data at the input of DDC is latched to CK. The data at the output of the DDC is latched to AFS. Thus, it is observed that CK/AFS = *total decimation rate*. The on-time of AFS equals one ACK clock cycle. Also, CK/ACK is called the *clock ratio*. Since the AFS is tied to ACK, the ratio ACK/AFS has to be an integer. (Since AFS occurs after certain number of ACK clock cycles) *Thus, the clock ratio should always divide the total decimation rate*. Taking this result into consideration, *the clock ratio can be any integer from '1' to 'total decimation rate'*.

The DDC and DUC ACK and AFS will have the same frequency but a phase offset between them. (as shown in the Figure 1). Instead of changing the clock phase offsets of the two ACKs (which is not possible), shift the data with respect to one of the clocks.



The TSW4100 uses a synchronizing logic programmed in the FPGA on TSW4100 to synchronize the data to the clocks. What this does is that it simply delays the data present on the DUC input bus with respect to the DDC output ACK signal based on the sync delay provided by the user.

The sync delay (TSW4100 GUI) is nothing but number of CK clocks between AFS and data A. Note that the user can always delay data and not advance it. Relative to a particular point in the AFS signal, data A can be pushed anywhere from 0 CK cycles to 'total decimation rate' clock cycles. (since the maximum value of clock ratio = total decimation rate). *Thus, sync delay is any number between 0 to the 'total decimation rate'*. Any number exceeding the 'total decimation rate' leads to a configuration of signals which is redundant.

**Point to be notes about sync delay:** The TSW4100 GUI gives us the flexibility to set the sync delay to any integer multiples of CK clocks. However, since the data is always synchronized to the ACK, theoretically, any values of sync delay that offsets the data relative to ACK are meaningless. But, on a more pragmatic scale this is not observed to be true due to the imperfections in the synchronizing logic.

### Data Frame Length

The number of bits of data that is output by GC5016 is asserted by the equation mentioned below.

Data frame length = floor (bits/pins) x (2 if complex) x (n channels if TDM).

Where,

floor (x) = least integer greater than x

TDM = time division multiplexed channels, if any Now, there should be sufficient ACK clocks between the successive data frames; else there would be data corruption. Number of ACK clocks between two data frames (or two AFS is) = total decimation rate/clk ratio

Thus,

Data frame length = floor (bits/pins) x (2 if complex) x (n channels if TDM) <= Number of ACK clocks between two data frames (or two AFS pulses) = total decimation rate/clk ratio

For TSW4100, floor (bits/pins) = floor (16/16) =1, since 16 pins are used for 16 bits (see the TSW4100 schematic)

#### The key results from the above discussion are mentioned in the equations below:

- 1. CK/AFS = total decimation rate
- 2. On-time of AFS equals one ACK clock cycle.
- 3. CK/ACK = clock ratio
- 4. The clock ratio can be any integer from '1' to 'total decimation rate'



- 5. The clock ratio should always divide the total decimation rate
- 6. Sync delay is any number between 0 to the 'total decimation rate'
- Data frame length = floor (bits/pins) x (2 if complex) x (n channels if TDM) <= Number of ACK clocks between two data frames (or two AFS pulses) = total decimation rate/clk ratio

Note: Constraints (2) and (4) are taken care of by the TSW4100 software.

Thus, in order to synchronize the data, a trial and error method needs to be followed where all possible values of syc delays are experimented and the value which gives the best possible outcome is assigned as the sync delay for a particular GC5016 configuration. (This method is mentioned as the Oscilloscope Method of Synchronization in the User's guide). The various configurations of GC5016 can then be calibrated to the sync delays assigned to them and theoretically, this experiment should be repeatable. However, it is observed in a more pragmatic scenario that this never happens. The value of the sync delay that gives the best outcome is never repeatable for the same configuration of GC5016 (This is due to the glitch in the FPGA logic used on the board)

In order to overcome the above constraint, a method has been developed below which always synchronizes data for a zero sync delay. The only constraint here is that the total decimation rate <=16. This method is foolproof and suffices most of the applications since the total decimation rate is below 16 for most of the customers.

## **Syncronization at Lower Decimation Rates**

It is observed that if the ACK frequency is decreased (clk ratio is increased), then the delay between successive AFS pulses and hence the succesive data frames decreases, since the data is latched for more time. At clk ratio = total decimation rate, the successive data are adjacent to one another. The AFS is always high. Thus, no synchronization is needed in this case.

The above discussion assumes that the data frame is just one bit long (*split IQ mode*). In 4 channel mode of TSW4100, since the data strobe consists of I and Q (2 bits), the clk ratio =  $\frac{1}{2}$  x Total Decimation rate. And so on, for other data frames of other lengths.

Using this observation, the case of clk ratio = total decimation rate should always work for Split IQ mode. Similarly, if the of clk ratio =  $\frac{1}{2}$  x Total Decimation rate should always work for 4 channel mode. The sync delay is zero in both the cases. (Note: The TSW4100 software sets the clk ratio to the total decimation rate by default)

However, this method works only for lower decimation rate, due to practical constraints of realizing the circuit with a data convertor. At higher decimation rates (>16), if the clk ratio is assigned close to the total decimation rate, then the ACK clock will be too slow to operate the data convertors used in the signal chain.



## **Synchronization Test**

Before starting this test, make sure that the data setting in the input options tab of the DAC5688 is set to 2's complement format. If the setting in this tab is offset binary, then erroneous results are obtained in the synchronization test.

### A) Split IQ Mode (Spectrum Analyzer Method):

Pull open the TSW4100 GUI and configure it to look like Figure 2. TSW4100 is configured to set the 'clk ratio' equal to the total decimation rate. This configuration always synchronizes the DDC and DUC for all possible modes of channel configurations.

TSW4100GU	l_v2p01_resize					
ver.201 ABOUT Ch 1/2 © SPLIT IQ O 4 CHANNEL	Channel 1 Configure         OFF           CIC rate         8         IF (MHz)           PFIR rate         2         Cain (dB)         0           PFIR Max Taps = 511	Filter O Load O Design	1.5 Passband B// (MHz) 1 Ripple (dB)	1.25 50	CIC taps CIC taps CIC taps 3 ono Stopband Freqs (MHz) Stopband Amps (dB)	Interface cik ratio 15 Sync Delay 0 Sync SCK Pol • POS • NEG
CCS016 Outputs     Outputs     Outputs     Dual Real     Single Real     Nyquist Zone     Outputs     Teo     Outputs     Outputs	Channel 3 Configure OFF OC rate 8 F (MHz) 120 PFIR rate 2 Gain (dB) 0 PFIR Max Taps = 511	Filter Coad Design	1.5         Passbend EW (NHz)           1         Ripple (dB)	1.25	CC taps CC taps CCC a 5 no Stopband Freqs (MHz) Stopband Amps (dB)	Interface cit ratio 16 Sync Delay SCK Pol SCK Pol POS NEG
Save Plots (.bmp) Save Structs (.mat) Real Time Delay Program TSW4100 USB Interface	Configure SAVE OPEN E	3ase File Na	me TSW4100temp \$	Status		settings

Figure 2. Split IQ Mode

The user should observe a tone at the input frequency of 100.1 MHz as shown in the Figure 3 (The input should be within the passband of the filter and should not be exactly equal to the IF frequency). The signal experiences an attenuation of 7dBm through the ADC and DAC and 3dBm attenuation due to the cables. So, a tone should be observed at the input frequency with - 10dBm peak. This confirms the functionality of the digital repeater.

**Note:** There is a small signal trace at 120MHz; this is because the signal output by the signal generator has harmonics at frequencies other than the frequency that it is supposed to output



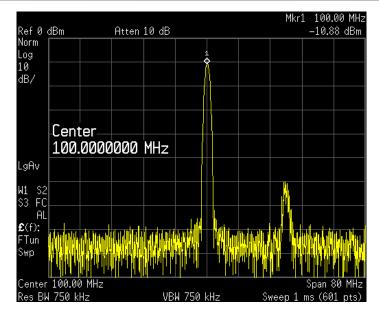


Figure 3. Output of the Spli IQ Mode

### B) 4 Channel Mode (Spectrum Analyzer Method):

Pull out the TSW4100 GUI and configure it look like Figure 4. TSW4100 is configured to set the 'clk ratio' equal to the ½ x total decimation rate. This configuration always synchronizes the DDC and DUC for all possible modes of channel configurations. All the four channels should be symmetric (should have identical configuration) to obtain desired results. (except for the IF frequency)

r. 2.01 ABOUT	Channel 1 Configure	Filter			DUC CIC taps	Interface
- Ch 1/2	CIC rate 8 IF (MHz) 100	O Load				clk ratio 8 Sync Delay
4 CHANNEL	PFIR rate 2 Gain (dB) 0	💿 Design	1.5 Passband BW (MHz)	1.25	Stopband Freqs (MHz)	0 Syr
Texas	PFIR Max Taps = 255		1.5 Ripple (dB)	50	Stopband Amps (dB)	SCK Pol
TRUMENTS	Channel 2 Configure	Filter	-			Interface
GC5016 Outputs	CiC sets T datas				DUC CIC taps	clk ratio 8
<ul> <li>Complex</li> </ul>	8 P (MHZ) 110	OLoad			DDC 05 0 no	Sync Delay
O Dual Real	PFIR rate 2 Gain (dB) 0		1.5 Passband BW (MHz)		Stopband Freqs (MHz)	0 Syn
Single Real		<ul> <li>Design</li> </ul>	1.5 Passband BVV (MHz)	1.25		SCK Pol
Nyquist Zone	PFIR Max Taps = 255		1.5 Ripple (dB)	50	Stopband Amps (dB)	POS O NEC
2	Channel 3 Configure	Filter				Interface
Clock (MHz) 160			-		DUC CIC taps	clk ratio 8
- Ch 3/4	CIC rate 8 IF (MHz) 130	O Load			O <sup>3</sup> Ono	Sync Delay
SPLIT IQ					DDC 05 CHO	0 Syn
4 CHANNEL	PFIR rate 2 Gain (dB) 0	<ul> <li>Design</li> </ul>	1.5 Passband BVV (MHz)	1.25	Stopband Freqs (MHz)	SCK Pol
lots	PFIR Max Taps = 255		1.5 Ripple (dB)	50	Stopband Amps (dB)	● POS ● NE
RX + TX PFIRs	Channel 4 Configure	Filter				Interface
RX/TX conv	OFF				DUC CIC taps	clk ratio 8
summed resp	CIC rate 8 IF (MHz) 140	OLoad				
	PFIR rate	Ŭ				Sync Delay
iave Plots (.bmp)	Gain (dB)	<ul> <li>Design</li> </ul>	1.5 Passband BW (MHz)	1.25	Stopband Freqs (MHz)	0 Syn
Save Structs (.mat)	PFIR Max Taps = 255		1.5 Ripple (dB)	50	Stopband Amps (dB)	SCK Pol     ONEC
teal Time Delay			1.5			

Figure 4. Four Channel Mode Configuration



The user should observe a tone at the input frequency as shown in the Figure 5 (The input should be within the passband of the filter and should not be exactly at the IF frequency). The signal experiences an attenuation of 7dBm through the ADC and DAC and 3dBm attenuation due to the cables. So, a tone should be observed at the input frequency with - 10dBm peak. This confirms the functionality of the digital repeater.

**Note:** There is a small signal trace at three other intermediate frequencies. Because the signal output by the signal generator has harmonics at frequencies other than the frequency that it is supposed to output.

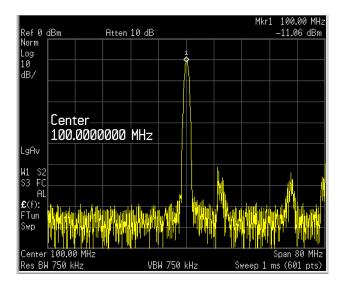


Figure 5. Output of four channel Mode

#### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Mobile Processors	www.ti.com/omap		
Wireless Connectivity	www.ti.com/wirelessconnectivity		
	TI 505 0		

**TI E2E Community Home Page** 

e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2012, Texas Instruments Incorporated